

New UMTS Products to be Based on TI's OMAP(TM) 2 Architecture and NTT DoCoMo's W-CDMA Technology

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Texas Instruments Incorporated (TI) (NYSE:TXN) and NTT DoCoMo, Inc., announced a joint agreement to develop a cost-competitive, multimode UMTS (W-CDMA/ GSM/GPRS) chipset to serve the Japanese, U.S. and worldwide 3G handset market. This collaboration further strengthens a long-standing relationship between the two industry leaders to drive the faster market adoption of 3G handsets.

An integrated UMTS digital baseband and applications processor will be developed based on TI's OMAPTM 2 architecture and NTT DoCoMo's W-CDMA technology for NTT DoCoMo handsets and other 3G handsets worldwide. Additionally, the agreement will include development and testing of power management, RF and protocol software that will be made available as system solutions to TI's worldwide customer base.

Japan's premier mobile communications company, NTT DoCoMo is a leader in 3G services with more than 4 million subscribers in the rapidly growing Japanese market. NTT DoCoMo has had a close relationship with TI and uses TI's OMAP family of applications processors in its FOMA phones. In addition, TI's RF and power management products are utilized in some NTT DoCoMo FOMA phones on the market today.

To be manufactured using TI's 90nm technology, this new UMTS solution will be the first to integrate TI's OMAP 2 applications processor



with a digital baseband. TI's OMAP 2 "All-in-One" architecture provides the foundation for mobile device manufacturers to merge today's most compelling high-end consumer electronics in smartphones and other converged portable multimedia devices. OMAP 2 processors will redefine mobile entertainment and communications as the first solutions to deliver consumer electronics-quality user experiences to the wireless industry, such as digital TV, hi-fi music with 3D effects, up to DVD-quality video, high-end gaming console functionality, best-in-class color display, and digital cameras with up to 6 megapixels.

Expanding upon TI's existing UMTS chipset portfolio, TI will also develop a series of UMTS chipsets for the general market based on this solution with a roadmap encompassing multi-mode EDGE and higher data rate HSDPA offerings. The complete system solution will include the integrated digital baseband and OMAP 2 applications processor, as well as RF and power management devices.

"TI looks forward to continuing to support NTT DoCoMo as it works to bring advanced multimedia services to consumers. By joining forces, TI and NTT DoCoMo create a winning solution for the UMTS market," said Gilles Delfassy, TI senior vice president, wireless terminals business unit.

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